GENERAL GUIDLINES

STORING ENCAPSULATED SEMICONDUCTOR DEVICES

- Avoid storage locations where devices may be exposed to water (wet, rain, dew condensation, etc) and/or direct sunlight.

- Follow the precautions printed on the packing label of the device for transportation and storage.

- Keep the storage location at temperature and relative humidity within a range of 5°C to 35°C and 40% to 70%, respectively. The lower the better.

- Do not store the products in locations with corrosive chemicals/gases and/or in dusty conditions.

- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause dew condensation, resulting in lead oxidation or corrosion, which will deteriorate the solder ability of leads.

- When re-storing devices after removal from their packing, use anti-static containers.

- Always work at an ESD safe workstation and observe ESD suppression methods when handling semiconductor devices.

- Do not allow loads to be applied directly to devices while they are in storage. (I.e. do not stack)

- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the device leads for signs of corrosion or oxidation that can inhibit soldering.

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